

ABSTRACT

An element such as a semiconductor wafer or other body is provided with flexible leads, the tip ends of which project over the front surface of the element. The tips of the flexible leads are spaced apart from the front surface and are independently moveable with respect to the element. The flexible leads may be curved in a plane parallel to the front surface of the element, or may be curved so that the tip end of each flexible lead is disposed further from the front surface of the element than the main body of the flexible lead.

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